ASSOCIATION C	© Copyright 2005.	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under be international and Pan-American copyright conventions.		der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and Mfg Information				
upplier I	Information								,					
Company name*			Company unique ID			τ	Unique ID Authority				Response Date*			
nsemi										2023-06-08				
Contact Nan	me	Title - Contact			P	Phone - Contact*				Email - Contact*				
Product-En	v-Stewards	Product Enviro Compliance			I	NA				Product-Env-Stewards@onsemi.com				
uthorized l	Representative*	Title - Representative			P	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com			
F	Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	N	Manufacturing Site		Veight*	UOM	Unit Type
		FAN23SV60AMPX 10 A Buck F		10 A Buck Regulate	ck Regulator		2023-06-08	06-08 PBB		ВВ	8	6.261	mg	Each
	curing Proccess Inform													
Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy J-S	STD-020 MSL	Rating		ess Body Te	T .		Temperatu	re Numb	er of Reflow Cyc	eles	
M	Matte Tin (Sn) - annealed		CU Alloy	1			260		C	30	second	ls 3		
omments														
vel 1 - max	ximum time at peak tempera	ture during sol	dering is 10-3	30 seconds										
or more inf	formation regarding materia	al composition	please refer t	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed						
RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to suc										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	4.062	mg	Supplier	Zinc (Zn)	7440-66-6		0.005	mg
			Supplier	Iron (Fe)	7439-89-6		0.097	mg
			Supplier	Copper (Cu)	7440-50-8		3.96	mg
Die	1.14	mg	Supplier	Silicon (Si)	7440-21-3		1.14	mg
Die Attach Solder	1.568	mg	Supplier	Silver (Ag)	7440-22-4		0.0392	mg
			A	Lead (Pb)	7439-92-1	7a	1.4504	mg
			Supplier	Tin (Sn)	7440-31-5		0.0784	mg
Lead Frame	30.983	mg	Supplier	Silver (Ag)	7440-22-4		0.282	mg
			Supplier	Zinc (Zn)	7440-66-6		0.04	mg
			Supplier	Iron (Fe)	7439-89-6		0.744	mg
			Supplier	Copper (Cu)	7440-50-8		29.917	mg
Mold Compound-Black	45.784	mg	Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		4.12	mg
			Supplier	Carbon Black (C)	1333-86-4		0.458	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		40.3	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.906	mg
Plating	1.78	mg	Supplier	Tin (Sn)	7440-31-5		1.78	mg
Wire Bond - Au	0.658	mg	Supplier	Gold (Au)	7440-57-5		0.658	mg
Wire Bond - Cu	0.286	mg	Supplier	Palladium (Pd)	7440-05-3		0.0057	mg
			Supplier	Copper (Cu)	7440-50-8		0.2803	mg